AMENDMENTS TO THE CLAIMS:

This listing of the claims replaces all prior versions and listing of the claims in the present application.

Listing of Claims:

1-25. (canceled).

26. (withdrawn/currently amended) A flame retardant epoxy resin composition comprising an epoxy resin (A), a phenolic resin (B), an inorganic filler (C) and a curing accelerator (D):

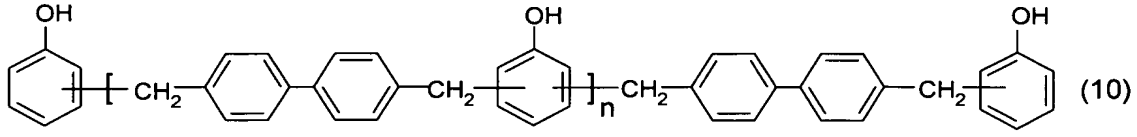
wherein

said composition is composed of the inorganic filler (C) and resin components other than the inorganic filler (C) that are comprising the epoxy resin (A), the phenolic resin (B) and the curing accelerator (D), but said composition comprises no flame retardant material nor flame retardant auxiliary;

said composition is an epoxy resin composition for semiconductor encapsulation which cures into a product exhibiting excellent flame retardancy without any flame retardant material nor flame retardant auxiliary;

said composition contains the inorganic filler (C) in the equal amount to a content of W (wt%) for the inorganic filler (C) in a cured article being obtainable by curing the composition, wherein the W (wt%) is selected in range of $60 < W \leq 95$;

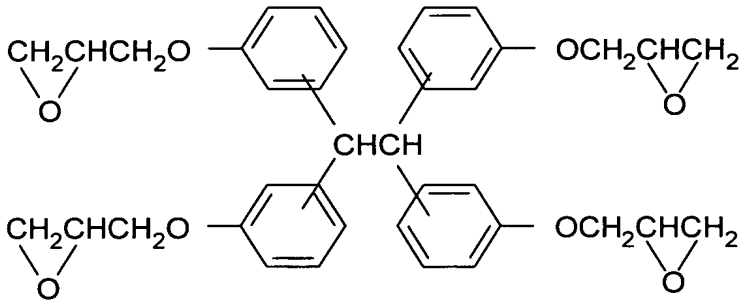
the phenolic resin (B) is one or a mixture of two or more phenolic resins containing biphenyl derivative having no hydroxyl group in the molecule represented by formula (10)):



(10)

wherein n - 0 to 10,

the epoxy resin (A) is a tetraphenylolethane epoxy resin consisting essentially of an epoxy resin represented by formula (3):



(3)

the inorganic filler (C) is one or a mixture of two or more fillers selected from the group consisting of fused silica, crystalline silica, or silicon nitride, and

a ratio (OH/Ep) of a phenolic hydroxyl group number (OH) of the total phenolic resin to an epoxy group number (Ep) of the total epoxy resin is $1.0 \leq (OH/Ep) \leq 2.5$;

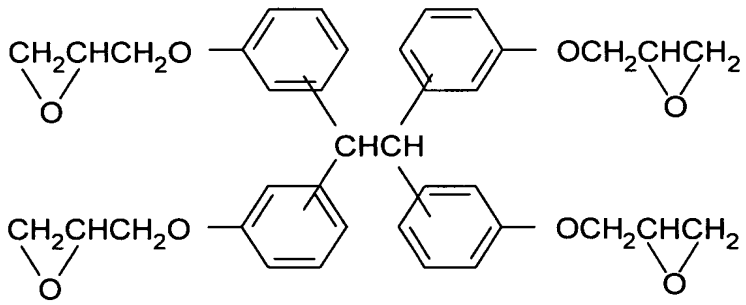
the moiety of the biphenyl derivative having no hydroxyl group is included in a crosslinked structure of the cured article; and

a flexural modulus E (kgf/mm^2) at 240 ± 20°C of the cured article is a value satisfying $0.30W - 13 \leq E \leq 3.7W - 184$ in the case of $60 < W \leq 95$, and the cured article forms a foamed layer during thermal decomposition or at ignition to exert flame retardancy.

27. (withdrawn) The epoxy resin composition according to Claim 26, wherein the flexural modulus E (kgf/mm^2) at 240 ± 20 °C of the cured article is a value satisfying $0.30W - 10 \leq E \leq 3.7W - 199$ value in the case of $60 < W \leq 95$.

28. (withdrawn) The epoxy resin composition according to Claim 26, wherein the ratio (OH/Ep) is 1.0.

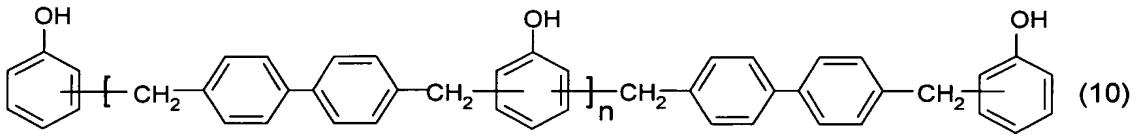
29. (withdrawn) The epoxy resin composition according to Claim 28, wherein the epoxy resin (A) is a tetraphenylol-ethane epoxy resin represented by formula (3):



(3)

, and

the phenolic resin (B) is a phenolbiphenylaralkyl resin represented by formula (10):



(10)

wherein n = 0 to 10.

30. (withdrawn/currently amended) A flame retardant epoxy resin composition comprising an epoxy resin (A), a phenolic resin (B), an inorganic filler (C) and a curing accelerator (D):

wherein

said composition is composed of the inorganic filler (C) and resin components other than the inorganic filler (C) that are comprising the epoxy resin (A), the phenolic resin (B) and the curing accelerator (D), but said composition comprises no flame retardant material nor flame retardant auxiliary;

said composition is an epoxy resin composition for semiconductor encapsulation which cures into a product exhibiting excellent flame retardancy without any flame retardant material nor flame retardant auxiliary;

said composition contains the inorganic filler (C) in the equal amount to a content of W (wt%) for the inorganic filler (C) in a cured article being obtainable by curing the composition, wherein the W (wt%) is selected in range of $60 \leq W \leq 95$;

the phenolic resin (B) is one or a mixture of two or more phenolic resins containing biphenyl derivative having no hydroxyl group in the molecule,

the epoxy resin (A) is a mixture of two or more epoxy resins containing a biphenyl derivative,

the inorganic filler (C) is one or a mixture of two or more fillers selected from the group consisting of fused silica, crystalline silica, or silicon nitride, and

a ratio (OH/Ep) of a phenolic hydroxyl group number (OH) of the total phenolic resin to an epoxy group number (Ep) of the total epoxy resin is 1.0;

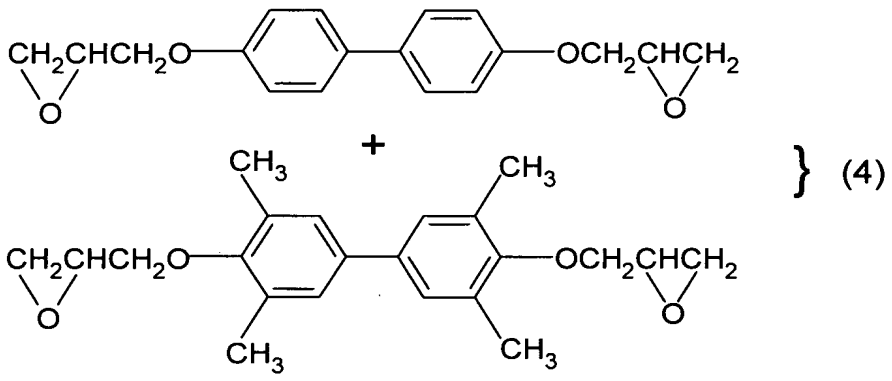
the moiety of the biphenyl derivative having no hydroxyl group is included in a crosslinked structure of the cured article; and

a flexural modulus E (kgf/mm^2) at 240 ± 20°C of the cured article is a value satisfying $0.30W - 13 \leq E \leq 3.7W - 184$ in the case of $60 < W \leq 95$, and the cured article forms a foamed layer during thermal decomposition or at ignition to exert flame retardancy.

31. (withdrawn) The epoxy resin composition according to Claim 30, wherein the flexural modulus E (kgf/mm^2) at 240 ± 20 °C of the cured article is a value satisfying $0.30W - 10 \leq E \leq 3.7W - 199$ value in the case of $60 < W \leq 95$.

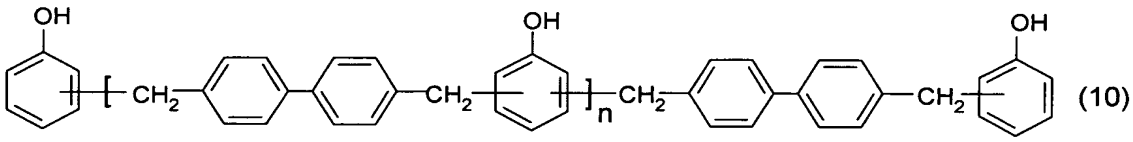
32. (withdrawn) The epoxy resin composition according to Claim 30, wherein the ratio (OH/Ep) is 1.0, and the W (wt%) is selected in range of 60 < W < 87.

33. (withdrawn) The epoxy resin composition according to Claim 30, wherein the epoxy resin (A) is a combinational mixture of biphenyl-4,4'-diglycidyl ether epoxy resin and 3,3',5,5'-tetramethylbiphenyl-4,4'-diglycidyl ether epoxy resin represented by formula (4):



, and

the phenolic resin (B) is a phenolbiphenylaralkyl resin represented by formula (10):



wherein n = 0 to 10.

34. (currently amended) A flame retardant epoxy resin composition comprising an epoxy resin (A), a phenolic resin (B), an inorganic filler (C) and a curing accelerator (D):

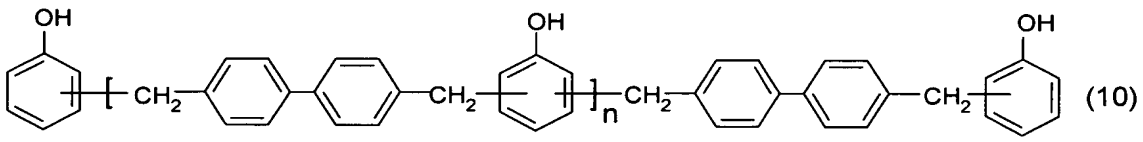
wherein

said composition is composed of the inorganic filler (C) and resin components other than the inorganic filler (C) that are comprising the epoxy resin (A), the phenolic resin (B) and the curing accelerator (D), but said composition comprises no flame retardant material nor flame retardant auxiliary;

said composition is an epoxy resin composition for semiconductor encapsulation which cures into a product exhibiting excellent flame retardancy without any flame retardant material nor flame retardant auxiliary;

said composition contains the inorganic filler (C) in the equal amount to a content of W (wt%) for the inorganic filler (C) in a cured article being obtainable by curing the composition, wherein the W (wt%) is selected in range of $60 < W \leq 95$;

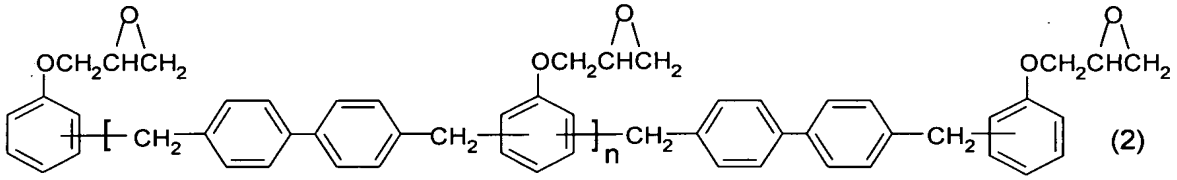
the phenolic resin (B) is one or a mixture of two or more phenolic resins containing biphenyl derivative having no hydroxyl group in the molecule represented by formula (10):



(10)

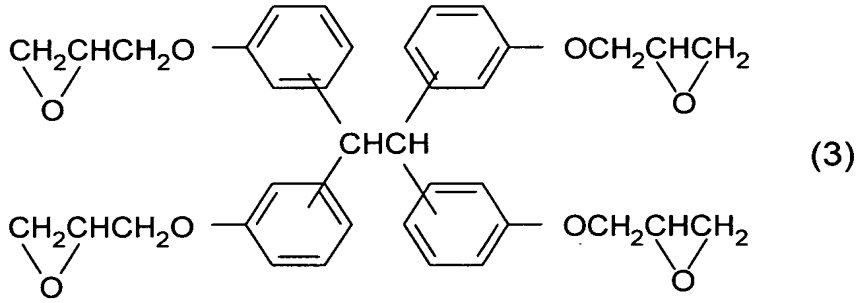
wherein n = 0 to 10,

the epoxy resin (A) is a mixture of a phenolbiphenylaralkyl epoxy resin containing a biphenyl derivative having no epoxy group in the molecule represented by formula (2):



wherein n = 0 to 10, and

a tetraphenylolethane epoxy resin consisting essentially of an epoxy resin represented by formula (3):



wherein the ratio of the tetraphenylolethane epoxy resin consisting essentially of an epoxy resin represented by formula (3) to the phenolbiphenylaralkyl epoxy resin of formula (2) is no less than 1/5,

the inorganic filler (C) is one or a mixture of two or more fillers selected from the group consisting of fused silica, crystalline silica, or silicon nitride, and

a ratio (OH/Ep) of a phenolic hydroxyl group number (OH) of the total phenolic resin to an epoxy group number (Ep) of the total epoxy resin is $1.0 \leq (OH/Ep) \leq 2.5$;

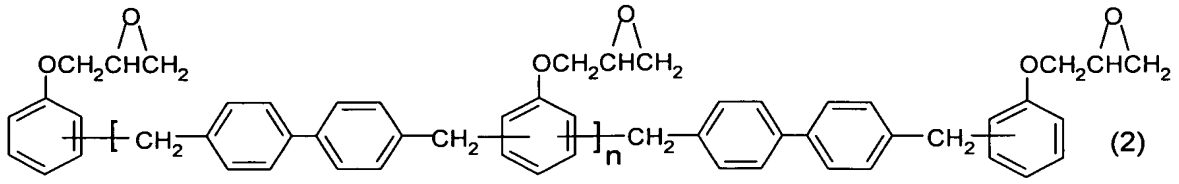
the moiety of the biphenyl derivative having no hydroxyl group is included in a crosslinked structure of the cured article; and

a flexural modulus E (kgf/mm^2) at 240 ± 20°C of the cured article is a value satisfying $0.30W - 13 \leq E \leq 3.7W - 184$ in the case of $60 < W \leq 95$, and the cured article forms a foamed layer during thermal decomposition or at ignition to exert flame retardancy.

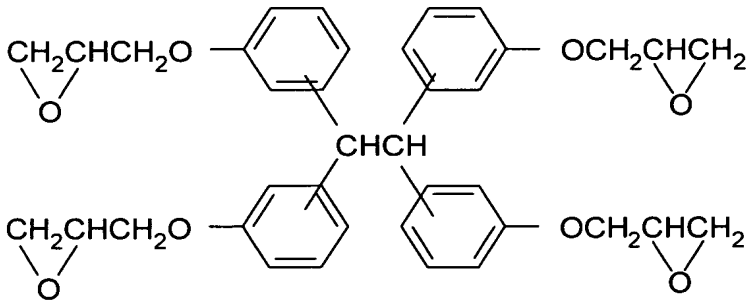
35. (previously presented) The epoxy resin composition according to Claim 34, wherein the flexural modulus E (kgf/mm^2) at 240 ± 20°C of the cured article is a value satisfying $0.30W - 10 \leq E \leq 3.7W - 199$ value in the case of $60 < W \leq 95$.

36. (currently amended) The epoxy resin composition according to Claim 35, wherein the ratio (OH/Ep) is 1.0.

37. (previously presented) The epoxy resin composition according to Claim 36, wherein the epoxy resin (A) is a combinational mixture of a phenolbiphenylaralkyl epoxy resin represented by formula (2):

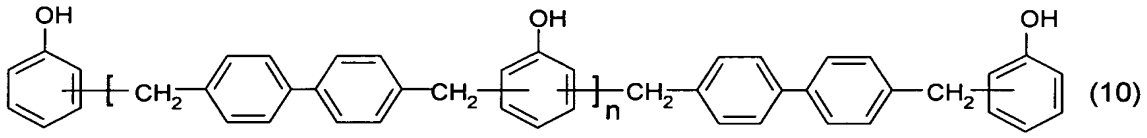


wherein n = 0 to 10, with a tetraphenylolethane epoxy resin represented by formula (3):



, and

the phenolic resin (B) is a phenolbiphenylaralkyl resin represented by formula (10):



wherein n = 0 to 10.

38. (withdrawn) A semiconductor device in which the epoxy resin composition described in Claim 26 is used as an encapsulating resin.

39-43. (canceled)

44. (withdrawn) A semiconductor device in which the epoxy resin composition described in Claim 30 is used as an encapsulating resin.

45. (previously presented) A semiconductor device in which the epoxy resin composition described in Claim 34 is used as an encapsulating resin.

46. (previously presented) The epoxy resin composition according to Claim 34,wherein the W (wt%) is selected in range of $60 < W < 87$.

47. (withdrawn) The epoxy resin composition according to Claim 26,

wherein the W (wt%) is selected in range of $60 < W < 87$.